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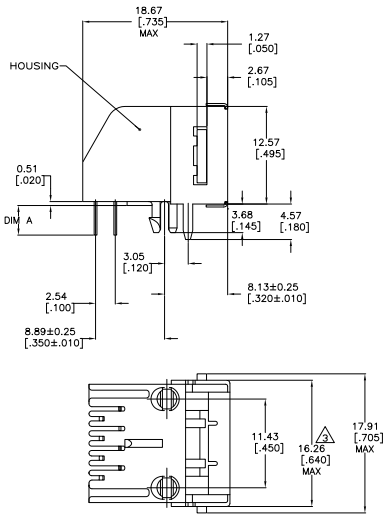
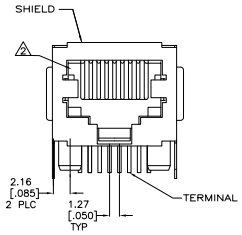
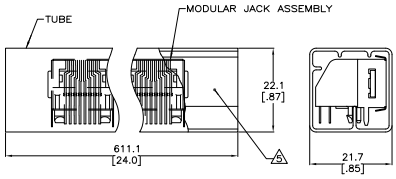
LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			D1	REVISED PER ECO-11-005140	28MAR11	RK	HMR







DETAIL B
SCALE 2:1

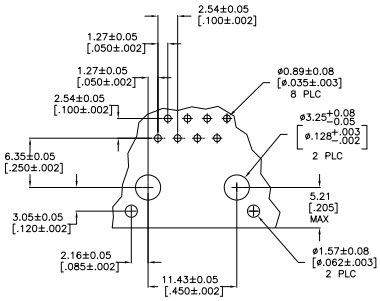
1. MATERIAL:
HOUSING – PBT POLYESTER, COLOR: BLACK
TERMINAL – 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE
SHIELD – 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0µm [.000120] MINIMUM THICK REFLOWED TIN

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

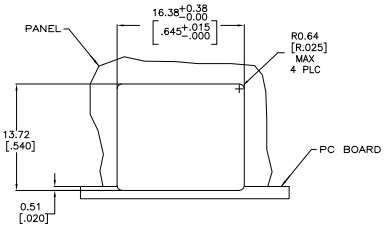
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE

4. BULK PACKAGED IN A TRAY

5. 32 ASSEMBLIES PACKAGED PER TUBE. SEE DETAIL B



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

DIM A	PACKAGED	PART NUMBER
1.78–2.79[.09±.02]	4	5555153–6
2.54–3.05[.11±.01]	4	5555153–5
3.30–4.32[.15±.02]	5	5555153–3
3.30–4.32[.15±.02]	4	5555153–1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± 0.13[.005]
3 PLC ± –
4 PLC ± –
ANGLES ± –

MATERIAL: SEE NOTE 1
FINISH: SEE NOTE 1

DWN: G. GARRETT/L.A.MAYER
CHK: P.BECCE
APVD: S.FLICKINGER
PRODUCT SPEC: 108–1163
APPLICATION SPEC: 114–2048
WEIGHT: –

TE Connectivity

NAME: MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS

SIZE: A1 | CAGE CODE: 00779 | DRAWING NO: C=5555153 | RESTRICTED TO: –

CUSTOMER DRAWING | SCALE: 4:1 | SHEET 1 OF 1 | REV: D1

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